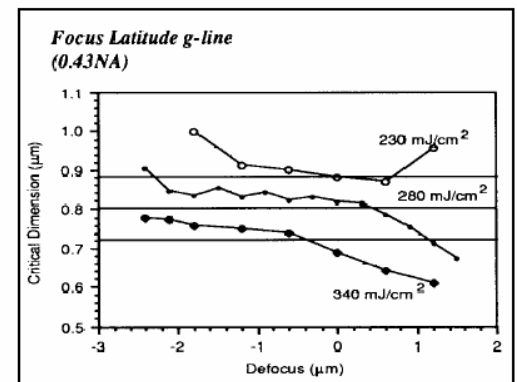
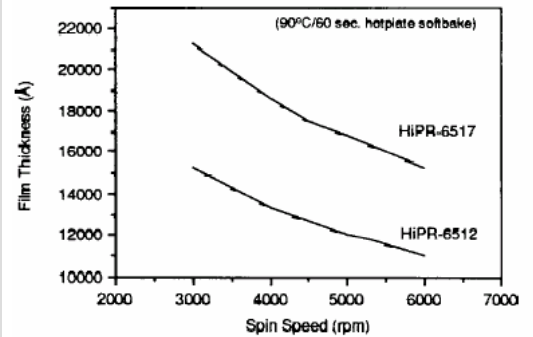


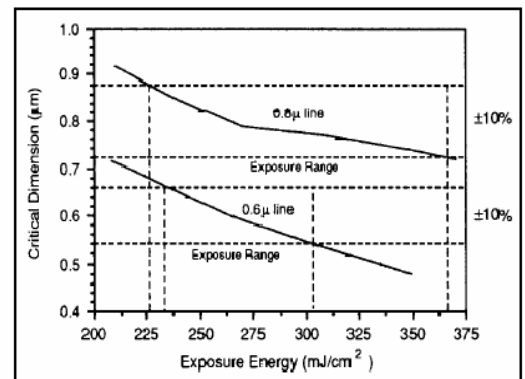
## HiPR 6500 Series

- HiPR 6500 is an advanced g- and i-line compatible positive photoresist in a safer solvent formulation.
- HiPR 6500 is a production viable system for both g-line and i-line exposure requiring <math> < 300 \text{ mJ/cm}^2 </math> utilizing TMAH developers with concentrations from .26N - .23N.
- Thermal stability exceeds most conventional products currently in production.
- HiPR 6500 demonstrates remarkable submicron production exposure latitude of greater than 40% for a 10% Critical Dimension window at geometries of  $0.8 \mu\text{m}$ .
- Near vertical profiles down to  $0.5 \mu\text{m}$  resolution.
- Uniquely formulated for increased photospeed allowing higher production throughput for both submicron g-line and i-line steppers.
- Thermal stability characteristics ( $>125^\circ\text{C}$ ) provide a robust, harsh plasma etch tolerance.
- Compatible with established FUJIFILM developers for ease of implementation.
- Ethyl lactate/EEP Solvent formulation permits a safer workplace environment.

**Spin Speed Curve**



**Exposure Latitude g-line**



Technical Data	HiPR 6512	HiPR 6517	HiPR 6520	HiPR 6517gh	HiPR 6517HC
Solids (%) Min.	26.5	29.8	32	31.9	29.75
Solids (%) Max.	27.5	30.8	33	33.9	31.75
Viscosity (cps) Min.	33.8	53.5	90	36	59.5
Viscosity (cps) Max	36.2	63.5	100	43	69.5
Water Content	<math> < 0.5\% </math>	<math> < 0.5\% </math>	<math> < 0.5\% </math>	<math> < 0.5\% </math>	<math> < 0.5\% </math>
Filtration	0.2 micron				
Refractive Index	1.6441	1.65	1.645	1.6544	1.6222
Flash Point	55°C (closed cup)				
Trace Metals None >	50ppb	100ppb	50ppb	200ppb	200ppb